

OIP232-1170

2U Rack Server



2U rack server with 32 DDR5 memory slots and up to 12 front hot-swappable drive bays. Supports up to two 4th / 5th Gen Intel® Xeon® Scalable processors and double-width GPU expansion.

- 4th/5th Gen Intel® Xeon®
- 32× DDR5 · Up to 8TB
- 12 Hot-Swap Drive Bays
- 10 PCIe + 2 OCP 3.0
- Dual Double-Width GPU

2U Rackmount 32 DIMM Slots 12 Drive Bays DDR5 Memory GPU Ready OCP 3.0

Product Specification

COMPUTE & MEMORY	
Product Form	2U rackmount; 32 DIMM slots and 12 front drive bays.
CPU	Supports up to two 4th / 5th Gen Intel® Xeon® Scalable processors, with a maximum TDP of 350 W. Supported processors include Intel® Xeon® 4510 and Intel® Xeon® 6526Y.
Memory	32 onboard DIMM slots. Supports 32 GB / 64 GB / 128 GB / 256 GB DIMMs, up to 8 TB total memory; DDR5 4800 MHz, up to DDR5 5200 MHz.
STORAGE, EXPANSION & NETWORK	
Drive Bays	Front: up to 12 hot-swappable 3.5 / 2.5 in SAS, SATA, or U.2 drives. Rear: optional two 2 × 2.5 in drive modules.
PCIe Slots	6 × full-height PCIe slots, 4 × half-height PCIe slots, and 2 × OCP 3.0 slots.
Network	Standard: 2 × 1000 Mb Ethernet ports (independent 2 × 1000 Mb). Optional 10 Gb network card with optical module.
GPU	Supports up to two full-height, full-length, double-width GPUs; actual graphics-card support is subject to compatibility.
I/O, RELIABILITY & MANAGEMENT	
External I/O	Front: 1 × VGA and 2 × USB 3.0. Rear: 1 × VGA, 1 × COM, 2 × USB 3.0, and 1 × RJ45 Gigabit management port.
Fans	4 hot-swappable N+1 redundant fans; supports 8038 / 8056 fan sizes.
Power Supply	Redundant AC 220 V 800 W / 1300 W / 1600 W / 2000 W / 2200 W / 2600 W power supplies, selected according to actual power requirements.
Management	1 dedicated RJ45 management port.
PHYSICAL & ENVIRONMENTAL	
Chassis	2U rackmount, 799 × 433.4 × 87.6 mm (D × W × H).
Rails	Standard rail kit × 1.
Operating Temperature / Humidity	5°C to 35°C; 20% to 80% RH, non-condensing.
Storage Temperature / Humidity	Short-term storage (≤ 72 h): -40°C to 70°C; 20% to 90% RH, non-condensing, including packaging. Long-term storage (> 72 h): 20°C to 28°C; 30% to 70% RH, non-condensing, including packaging.

Intel Xeon 32 DIMMs DDR5 GPU Ready OCP 3.0 Hot-Swap 10Gb Optional Redundant PSU